

8-Channel Serial to Parallel Converter with High Voltage Push-Pull Outputs, POL, Hi-Z, and Short Circuit Detect

Features

- ▶ HVCMOS® technology
- ▶ Operating output voltage of 250V
- ▶ Low power level shifting from 5.0 to 250V
- ▶ Shift register speed 8.0MHz @ $V_{DD} = 5.0V$
- ▶ 8 latch data outputs
- ▶ Output polarity and blanking
- ▶ Output short circuit detect
- ▶ Output high-Z control
- ▶ CMOS compatible inputs

Applications

- ▶ Piezoelectric transducer driver
- ▶ Braille driver
- ▶ Weaving applications
- ▶ Printer drivers
- ▶ MEMs
- ▶ Displays

General Description

The HV513 is a low voltage serial to high voltage parallel converter with 8 high voltage push-pull outputs. This device has been designed to drive small capacitive loads such as piezoelectric transducers. It can also be used in any application requiring multiple high voltage outputs, with medium current source and sink capabilities.

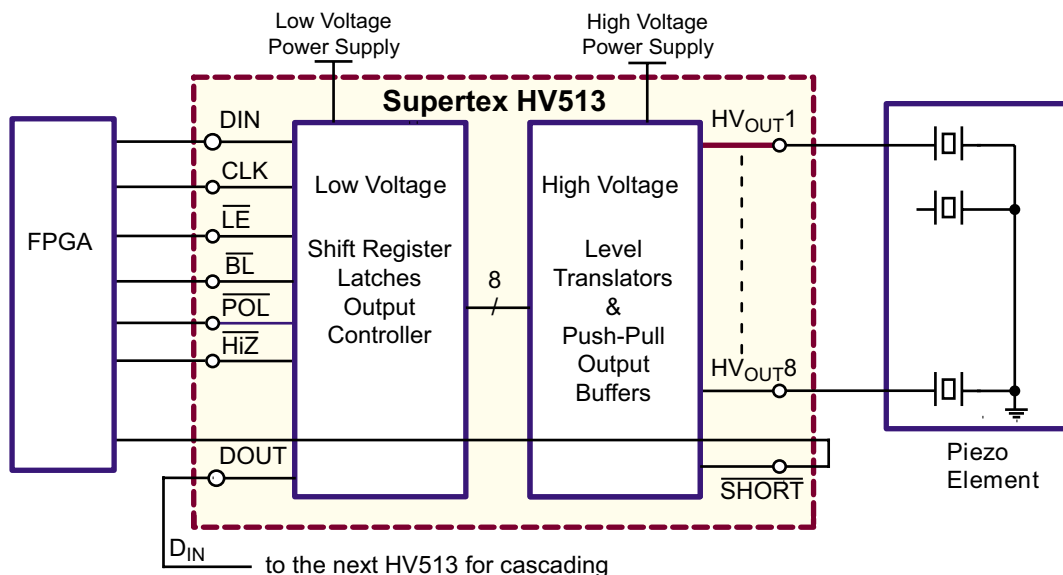
The device consists of an 8-bit shift register, 8 latches, and control logic to perform the polarity select and blanking of the outputs. Data is shifted through the shift register on the low to high transition of the clock. A data output buffer is provided for cascading devices. Operation of the shift register is not affected by the \overline{LE} , \overline{BL} , \overline{POL} , or the $\overline{Hi-Z}$ control inputs. Transfer of data from the shift register to the latch occurs when the \overline{LE} is high. The data in the latch is stored when \overline{LE} is low. A high-Z ($\overline{Hi-Z}$) pin is provided to set all the outputs in a high-Z state.

All outputs have short circuit protection that detects if the outputs have reached the required output state. If output does not track the required state, then the \overline{SHORT} pin will be low. This output will pulse low during the output transition period under normal operation; see SC Timing Diagram for details.

All outputs will have a break-before-make circuitry to reduce cross-over current during output state changes.

The \overline{POL} , \overline{BL} , \overline{LE} , and $\overline{Hi-Z}$ inputs have an internal pull up resistor.

Typical Application Circuit



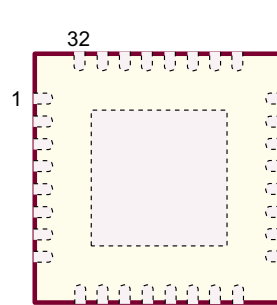
Ordering Information

| Device | Package Options | |
|--------|----------------------------------------------------------------------|-----------------------------------------------------------------------|
| | 32-Lead QFN 6.00x6.00mm body 0.80mm height (max) 0.50 pitch | 24-Lead SOW 15.40x7.50mm body 2.65mm height (max) 1.27 pitch |
| HV513 | HV513K7-G | HV513WG-G |

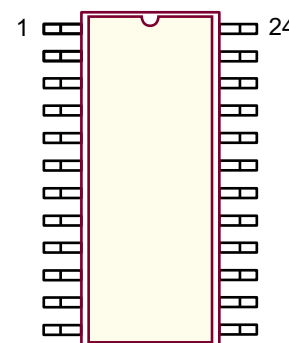
-G indicates package is RoHS compliant ('Green')



Pin Configurations



32-Lead QFN (K7)
(top view)



24-Lead SOW (WG)
(top view)

Absolute Maximum Ratings

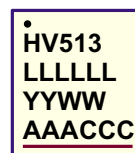
| Parameter | Value |
|-------------------------------------------------|-------------------------|
| Logic supply, V_{DD} | -0.5V to 6.0V |
| High voltage supply, V_{PP} | V_{DD} to 275V |
| Logic input levels | -0.5V to V_{DD} +0.5V |
| Ground current ¹ | 0.3A |
| High voltage supply current ¹ | 0.25A |
| Continuous total power dissipation ² | 750mW |
| Operating junction temperature | -40°C to +85°C |
| Storage temperature range | -65°C to +150°C |

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

Notes:

1. Connection to all power and ground pads is required. Duty cycle is limited by the total power dissipated in the package.
2. For operation above 25°C ambient derate linearly to 85°C at 12mW/°C.

Product Marking



L = Lot Number
YY = Year Sealed
WW = Week Sealed
A = Assembler ID
C = Country of Origin
— = "Green" Packaging

Package may or may not include the following marks: Si or

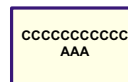
32-Lead QFN (K7)

Top Marking



YY = Year Sealed
WW = Week Sealed
L = Lot Number
C = Country of Origin
A = Assembler ID*

Bottom Marking



— = "Green" Packaging
*May be part of top marking

Package may or may not include the following marks: Si or

24-Lead SOW (WG)

Typical Operating Conditions

| Sym | Parameter | Min | Typ | Max | Units | Conditions |
|----------|--------------------------------|---------------|-----|----------|-------|------------|
| V_{DD} | Logic supply voltage | 4.5 | 5.0 | 5.5 | V | --- |
| V_{PP} | High voltage supply | 50 | - | 250 | V | Note 1 |
| V_{IH} | High-level input voltage | V_{DD} -0.9 | - | V_{DD} | V | --- |
| V_{IL} | Low-level input voltage | 0 | - | 0.9 | V | --- |
| T_J | Operating junction temperature | -40 | - | +85 | °C | --- |

Notes:

1. Below minimum V_{PP} the output may not switch.
2. Power-up sequence should be the following:
 1. Connect ground
 2. Apply V_{DD}
 3. Set all inputs (Data, CLK, Enable, etc.) to a known state
 4. Apply V_{PP}

Power-down sequence should be the reverse of the above

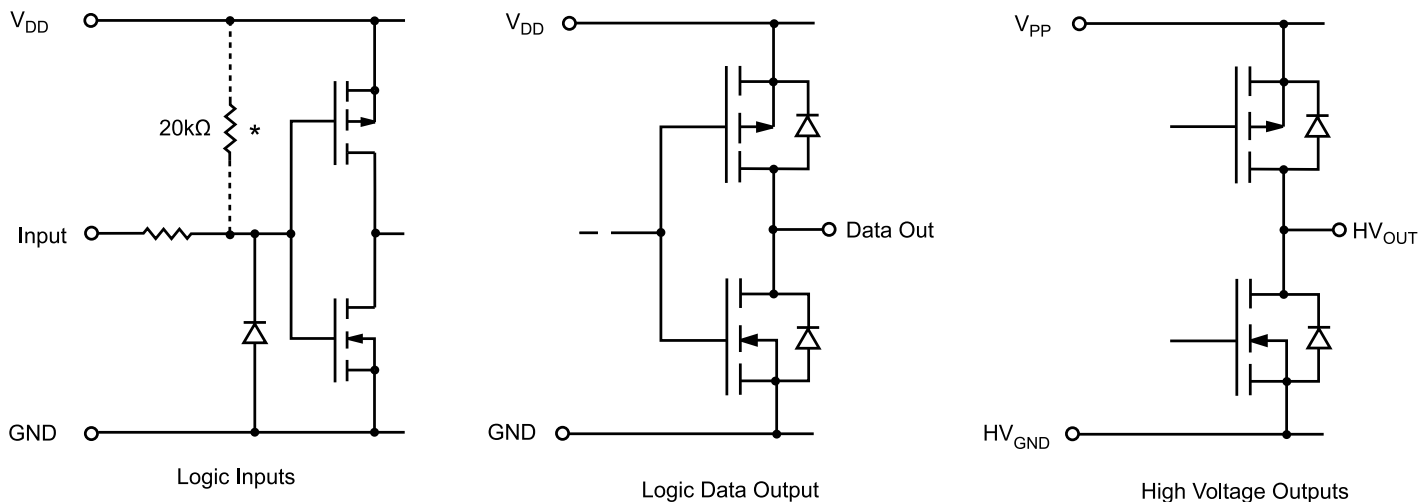
DC Electrical Characteristics (Over typical operating conditions unless otherwise specified, $T_j = 25^\circ\text{C}$)

| Sym | Parameter | Min | Typ | Max | Units | Conditions | |
|-----------|-----------------------------------|-------------------|------------------------|------|---------------|-------------------------------------------------------------|-----------------------------------------------------|
| I_{DD} | V_{DD} supply current | - | - | 4.0 | mA | $f_{CLK} = 8.0\text{Hz}$, $\overline{LE} = \text{Low}$ | |
| I_{DDQ} | Quiescent V_{DD} supply current | - | - | 0.1 | mA | All $V_{IN} = V_{DD}$ | |
| | | - | - | 2.0 | | All $V_{IN} = 0\text{V}$ | |
| I_{PP} | V_{PP} supply current | - | - | 100 | μA | $V_{PP} = 250\text{V}$, $f_{OUT} = 300\text{Hz}$, no load | |
| I_{PPQ} | Quiescent V_{PP} supply current | - | - | 100 | μA | $V_{PP} = 240\text{V}$, outputs are static | |
| I_{IH} | High-level logic input current | - | - | 10 | μA | $V_{IH} = V_{DD}$ | |
| I_{IL} | Low-level logic input current | - | - | -10 | μA | $V_{IL} = 0\text{V}$ | |
| | | - | - | -350 | | $V_{IL} = 0\text{V}$, for inputs w/pull-up resistors | |
| V_{OH} | High level output | HV _{OUT} | 140 | - | - | V | $V_{PP} = 200\text{V}$, $I_{HVOUT} = -20\text{mA}$ |
| | | Data out | $V_{DD} - 1.0\text{V}$ | - | - | | $I_{DOUT} = -0.1\text{mA}$ |
| V_{OL} | Low level output | HV _{OUT} | - | - | 60 | V | $V_{DD} = 4.5\text{V}$, $I_{HVOUT} = 20\text{mA}$ |
| | | Data out | - | - | 1.0 | | $I_{DOUT} = 0.1\text{mA}$ |

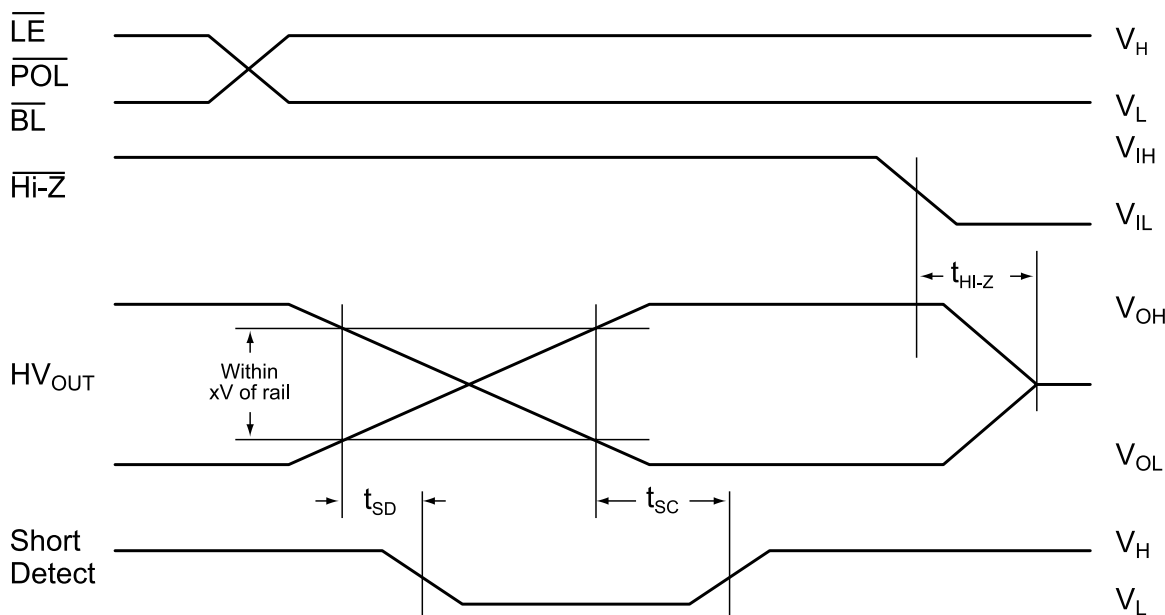
AC Electrical Characteristics (Over typical operating conditions unless otherwise specified, $T_j = 25^\circ\text{C}$)

| Sym | Parameter | Min | Typ | Max | Units | Conditions |
|------------------|--------------------------------------------------------|-----|-----|------|---------------|-------------------------------------------------------------------------|
| f_{CLK} | Clock frequency | 0 | - | 8.0 | MHz | --- |
| f_{OUT} | Output switching frequency (SOA limited) | - | 300 | - | Hz | $C_L = 50\text{nF}$, $V_{PP} = 200\text{V}$ |
| t_W | Clock width high and low | 62 | - | - | ns | --- |
| t_{SU} | Data setup time before clock rises | 15 | - | - | ns | --- |
| t_H | Data hold time after clock rises | 30 | - | - | ns | --- |
| t_{WLE} | Width of latch enable pulse | 80 | - | - | ns | --- |
| t_{DLE} | \overline{LE} delay time after rising edge of clock | 35 | - | - | ns | --- |
| t_{SLE} | \overline{LE} setup time before rising edge of clock | 40 | - | - | ns | --- |
| t_{OR}, t_{OF} | HV _{OUT} rise/fall time | - | - | 1000 | μs | $C_L = 100\text{nF}$, $V_{PP} = 200\text{V}$ |
| $t_{dON/OFF}$ | Delay time for output to start rise/fall | - | - | 500 | ns | --- |
| t_{DHL} | Delay time clock to D _{OUT} high to low | - | - | 110 | ns | $C_L = 15\text{pF}$ |
| t_{DLH} | Delay time clock to D _{OUT} low to high | - | - | 110 | ns | $C_L = 15\text{pF}$ |
| t_R, t_F | All logic inputs | - | - | 5.0 | ns | --- |
| t_{SD} | Output short circuit detection | - | - | 500 | ns | $C_L = 15\text{pF}$, Short to output fall of $\overline{\text{SHORT}}$ |
| t_{SC} | Output short circuit clear | - | - | 3000 | ns | Short clear to output rise of $\overline{\text{SHORT}}$ |
| t_{HI-Z} | Output $\overline{HI-Z}$ state | - | - | 500 | ns | --- |

Input and Output Equivalent Circuits



Short Circuit Detect Detail Timing



Note:
For V_{PP} greater than 150V:

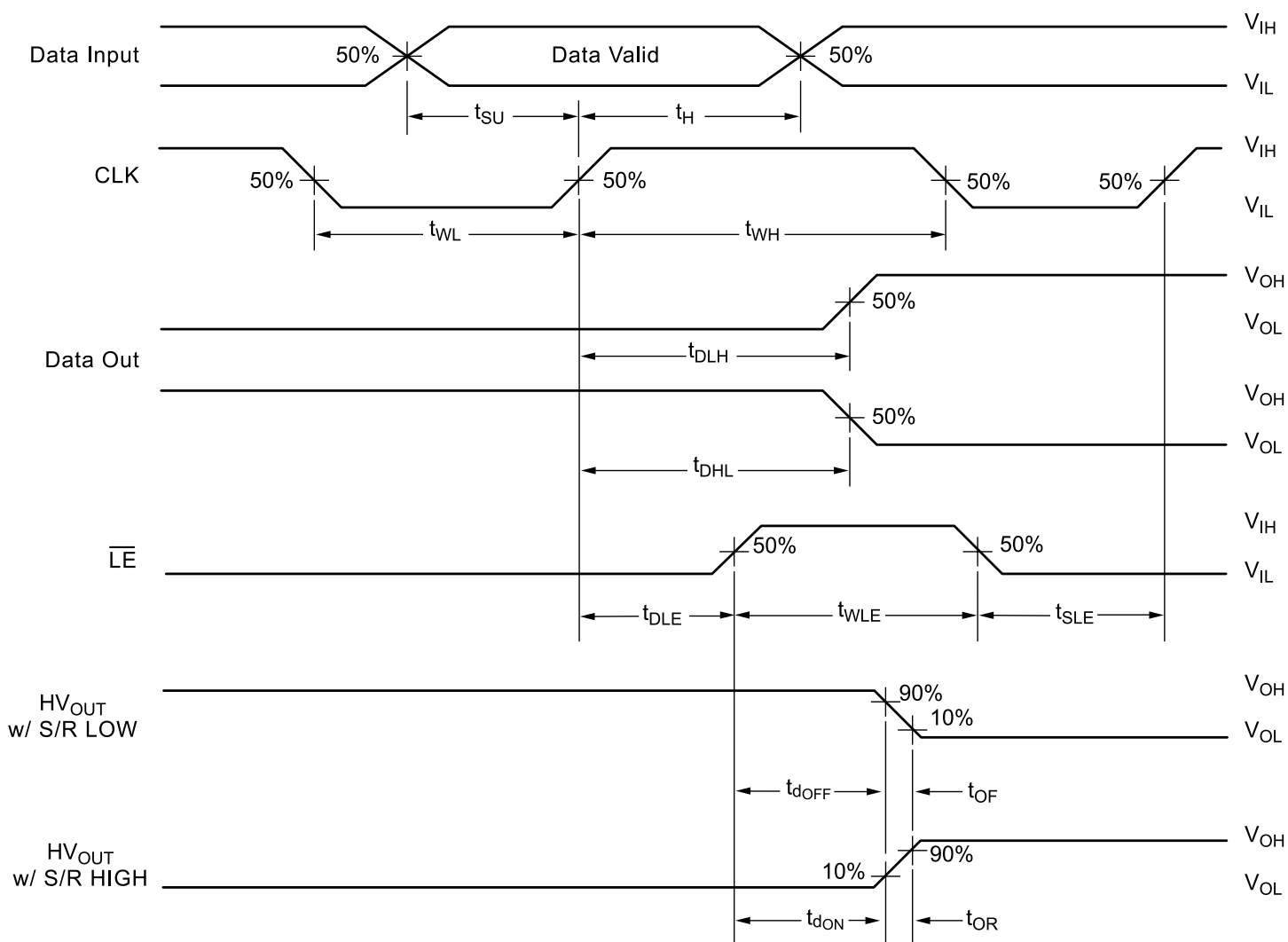
Short detect output will flag short conditions

- HV_{OUT} is higher than 10V when expected low
- HV_{OUT} is lower than $V_{PP} - 100V$ when expected high

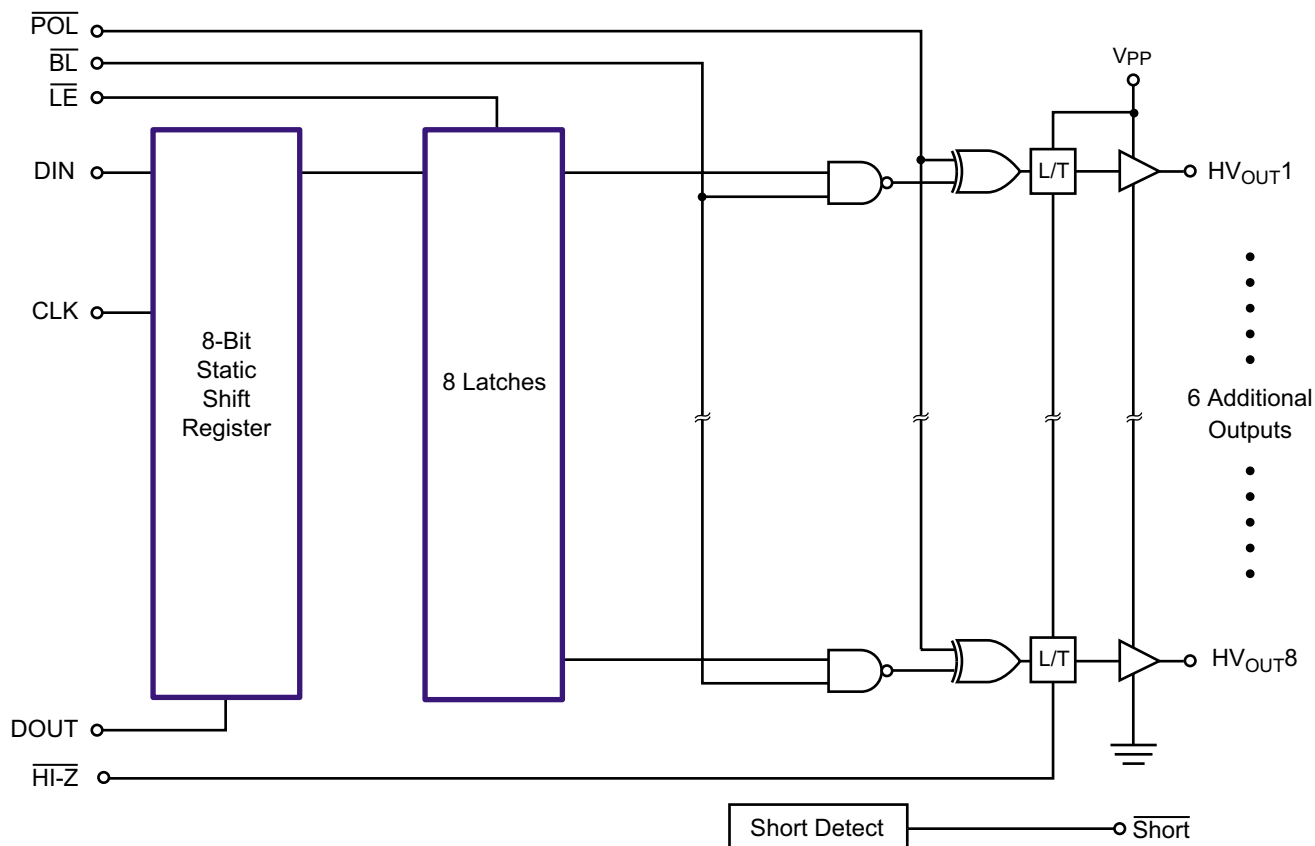
Short detect output will stay clear

- HV_{OUT} is lower than 2.0V when expected low
- HV_{OUT} is higher than $V_{PP} - 60V$ when expected high

Switching Waveforms



Functional Block Diagram



Note: POL, BL, LE, and HI-Z have internal 20kΩ pull-up resistors.

Function Table

| Function | Inputs | | | | | | Outputs | | |
|-----------------------|--------|-----|----|----|-----|------|----------------------|------------------------|---------------|
| | Data | CLK | LE | BL | POL | HI-Z | Shift Reg 1 2...8 | HV Outputs 1 2...8 | Data Out • |
| All on | X | X | X | L | L | H | • •...• | H H...H | • |
| All off | X | X | X | L | H | H | • •...• | L L...L | • |
| Invert mode | X | X | L | H | L | H | • •...• | • •...• (b) | • |
| Load S/R | H OR L | ↑ | L | H | H | H | H or L •...• | • •...• | • |
| Store data in latches | X | X | L | H | H | H | • •...• | • •...• | • |
| | X | X | L | H | L | H | • •...• | • •...• (b) | • |
| Transparent mode | L | ↑ | H | H | H | H | L •...• | L •...• | • |
| | H | ↑ | H | H | H | H | H •...• | H •...• | • |
| Outputs High-Z | X | X | X | X | X | L | • •...• | High impedance outputs | • |
| Outputs on | X | X | X | X | X | H | • •...• | • •...• | • |

Notes:
 H = high level, L = low level, X = irrelevant, ↑ = low-to-high transition
 • = dependent on previous stage's state before the last CLK or last LE high.

Pin Description - 32-Lead QFN (K7)

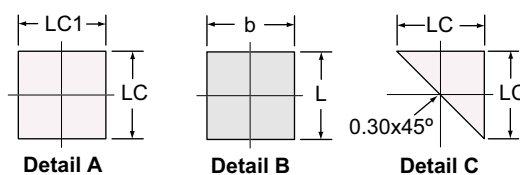
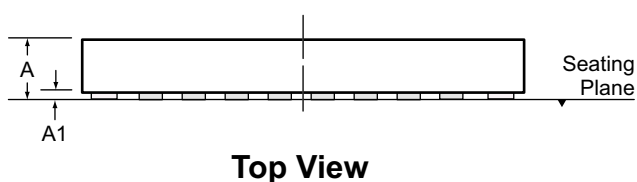
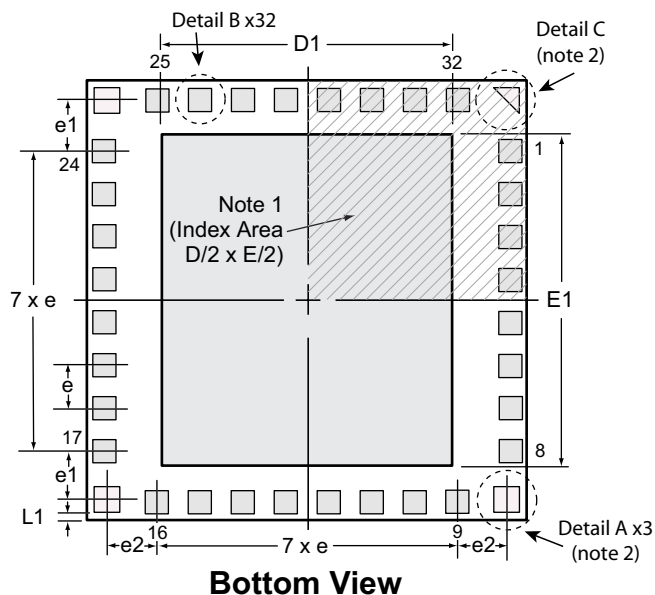
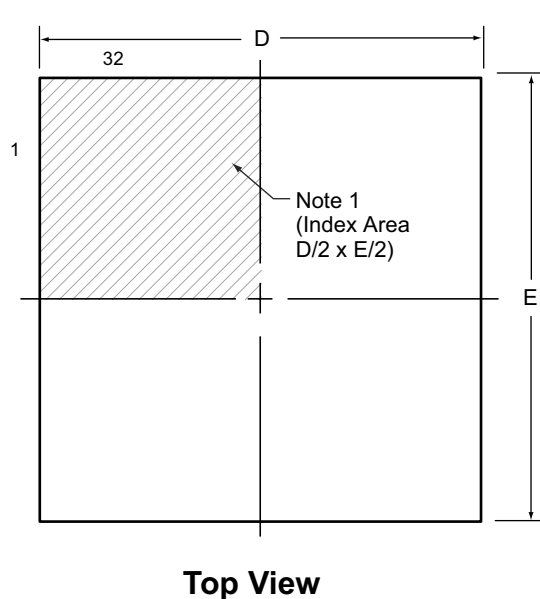
| Pin # | Function | Description |
|------------|---------------------------|--------------------------------------------------------------------------------|
| 1 | NC | No internal connection |
| 2 | | |
| 3 | | |
| 4 | LGND | Low voltage ground |
| 5 | HVGND | High voltage ground |
| 6 | | |
| 7 | NC | No internal connection |
| 8 | | |
| 9 | HV _{OUT} 1 | High voltage push-pull output |
| 10 | HV _{OUT} 2 | High voltage push-pull output |
| 11 | HV _{OUT} 3 | High voltage push-pull output |
| 12 | HV _{OUT} 4 | High voltage push-pull output |
| 13 | HV _{OUT} 5 | High voltage push-pull output |
| 14 | HV _{OUT} 6 | High voltage push-pull output |
| 15 | HV _{OUT} 7 | High voltage push-pull output |
| 16 | HV _{OUT} 8 | High voltage push-pull output |
| 17 | NC | No internal connection |
| 18 | | |
| 19 | VPP | High voltage supply |
| 20 | | |
| 21 | VDD | Logic supply voltage |
| 22 | DOUT | Data output |
| 23 | NC | No internal connection |
| 24 | | |
| 25 | $\overline{\text{BL}}$ | Blanking pin, logic input low sets all HV _{OUTS} low |
| 26 | NC | No internal connection |
| 27 | $\overline{\text{POL}}$ | Polarity bar input logic |
| 28 | CLK | Clock pin, shift registers shifts data on rising edge of input clock |
| 29 | $\overline{\text{LE}}$ | Latch enable bar input logic |
| 30 | $\overline{\text{SHORT}}$ | If output does not reach its required state, SHORT pin will output logic low |
| 31 | $\overline{\text{HI-Z}}$ | High impedance pin, logic input low sets all outputs in a high impedance state |
| 32 | DIN | Data input |
| Center Pad | V _{PP} | Center pad is at V _{PP} potential. Connect to VPP or leave floating. |

Pin Description - 24-Lead SOW (WG)

| Pin # | Function | Description |
|-------|---------------------------|--------------------------------------------------------------------------------|
| 1 | NC | No internal connection |
| 2 | VDD | Logic supply voltage |
| 3 | DOUT | Data output |
| 4 | $\overline{\text{BL}}$ | Blanking pin, logic input LOW sets all HV _{OUTS} low |
| 5 | $\overline{\text{POL}}$ | Polarity bar input logic |
| 6 | CLK | Clock pin, shift registers shifts data on rising edge of input clock |
| 7 | $\overline{\text{LE}}$ | Latch enable bar input logic |
| 8 | $\overline{\text{SHORT}}$ | If output does not reach its required state, SHORT pin will output logic LOW |
| 9 | $\overline{\text{HI-Z}}$ | High impedance pin, logic input LOW sets all outputs in a high impedance state |
| 10 | DIN | Data input |
| 11 | LGND | Low voltage ground |
| 12 | NC | No internal connection |
| 13 | HVGND | High voltage ground |
| 14 | | |
| 15 | HV _{OUT} 1 | High voltage push-pull output |
| 16 | HV _{OUT} 2 | High voltage push-pull output |
| 17 | HV _{OUT} 3 | High voltage push-pull output |
| 18 | HV _{OUT} 4 | High voltage push-pull output |
| 19 | HV _{OUT} 5 | High voltage push-pull output |
| 20 | HV _{OUT} 6 | High voltage push-pull output |
| 21 | HV _{OUT} 7 | High voltage push-pull output |
| 22 | HV _{OUT} 8 | High voltage push-pull output |
| 23 | VPP | High voltage supply |
| 24 | | |

32-Lead QFN Package Outline (K7)

6.00x6.00mm body, 0.80mm height (max), 0.50mm pitch



Notes:

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.
2. The 4 corner pads are for mechanical placement only, they are not internally connected.

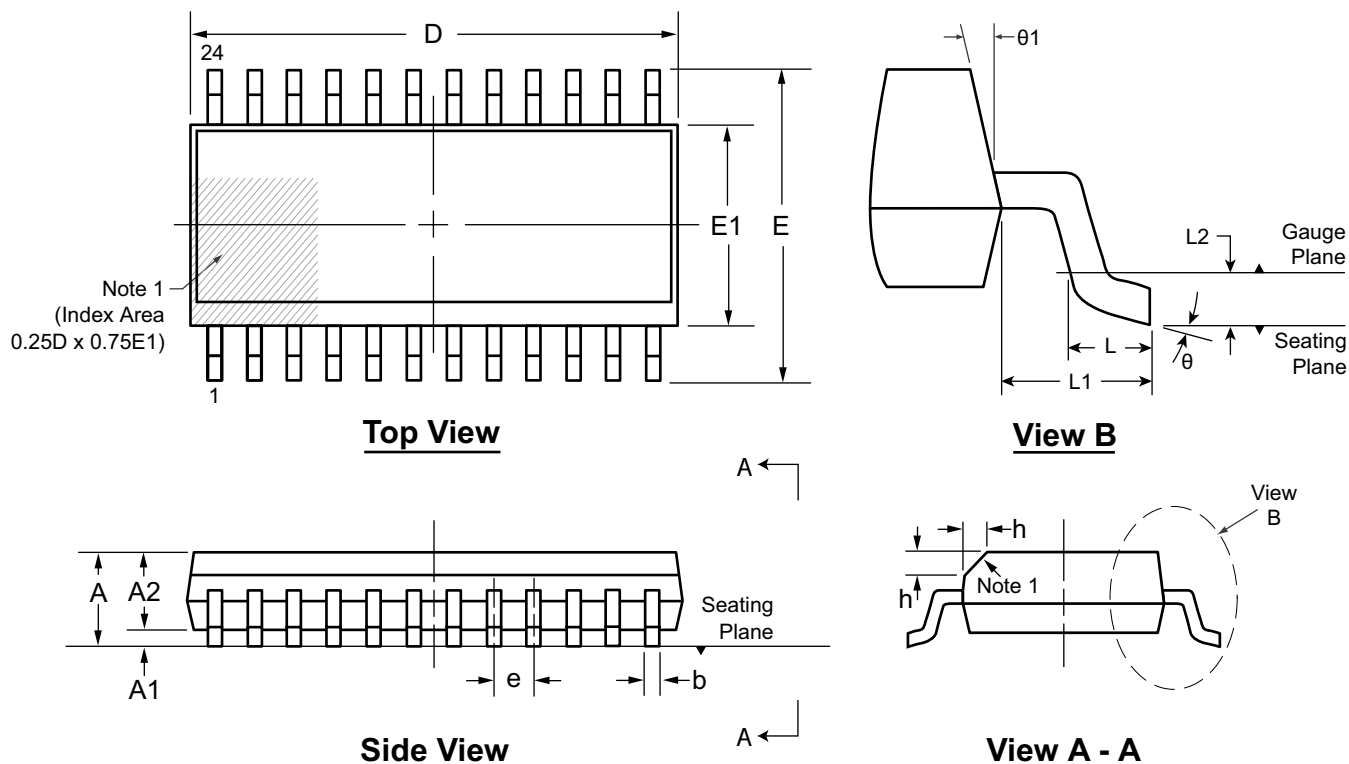
| Symbol | A | A1 | b | D | D1 | E | E1 | e | e1 | e2 | L | L1 | LC | LC1 |
|----------------|-----|------|------|------|------|------|------|------|----------|----------|-----------|------|----------|------|
| Dimension (mm) | MIN | 0.70 | 0.00 | 0.20 | 5.90 | 3.20 | 5.90 | 4.30 | 0.50 BSC | 1.00 REF | 0.975 REF | 0.20 | 0.10 REF | 0.20 |
| | NOM | 0.75 | - | 0.30 | 6.00 | 3.30 | 6.00 | 4.40 | | | | | | 0.30 |
| | MAX | 0.80 | 0.05 | 0.40 | 6.10 | 3.40 | 6.10 | 4.50 | | | | | | 0.40 |

Drawings not to scale.

Supertex Doc. #: DSPD-32QFNK76X6P050, Version B101008.

24-Lead SOW (Wide Body) Package Outline (WG)

15.40x7.50 body, 2.65mm height (max), 1.27mm pitch



Note:
 1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

| Symbol | | A | A1 | A2 | b | D | E | E1 | e | h | L | L1 | L2 | θ | θ1 |
|----------------|-----|-------|------|-------|------|--------|--------|-------|----------|------|------|----------|----------|----|-----|
| Dimension (mm) | MIN | 2.15* | 0.10 | 2.05 | 0.31 | 15.20* | 9.97* | 7.40* | 1.27 BSC | 0.25 | 0.40 | 1.40 REF | 0.25 BSC | 0° | 5° |
| | NOM | - | - | - | - | 15.40 | 10.30 | 7.50 | | - | - | | | - | - |
| | MAX | 2.65 | 0.30 | 2.55* | 0.51 | 15.60* | 10.63* | 7.60* | | 0.75 | 1.27 | | | 8° | 15° |

JEDEC Registration MS-013, Variation AD, Issue E, Sep. 2005.

* This dimension is not specified in the JEDEC drawing.

Drawings are not to scale.

Supertex Doc. #: DSPD-24SOWWG, Version E041309.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <http://www.supertex.com/packaging.html>.)

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